Chunqing Wang

List of Publications by Year
in descending order

Source: https://exaly.com/author-pdf/375306/publications.pdf

Version: 2024-02-01

327	4,005	33	49
papers	citations	h-index	g-index
		126907	197818

331	331	331	2577
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Evolution of Wafer Bonding Technology and Applications from Wafer-Level Packaging to Micro/Nanofluidics-Enhanced Sensing. , 2022, , 187-215.		0
2	Rapid fabrication of Cu/40-Î¼m thick full Cu3Sn/Cu joints by applying pulsed high frequency electromagnetic field for high power electronics. Materials Chemistry and Physics, 2022, 276, 125386.	4.0	3
3	Superior rate and long-lived performance of few-layered black phosphorus-based hybrid anode for lithium-ion batteries. Electrochimica Acta, 2022, 403, 139697.	5.2	15
4	Revealing the ductile-to-brittle transition mechanism in polycrystalline body-centered tetragonal tin (Sn) for cryogenic electronics. Journal of Alloys and Compounds, 2022, 903, 163948.	5.5	5
5	Communicationâ€"Hollow MnO_x@Nanoparticles Electrospun Fibers with High Porosity for Formaldehyde Removal at Room Temperature. Journal of the Electrochemical Society, 2022, 169, 027518.	2.9	0
6	High-Efficient Vacuum Ultraviolet-Ozone Assist-Deposited Polydopamine for Poly(lactic-<i>co</i>-glycolic acid)-Coated Pure Zn toward Biodegradable Cardiovascular Stent Applications. ACS Applied Materials & Interfaces, 2022, 14, 3536-3550.	8.0	16
7	Robust Cuâ€"Cu Bonding with Multiscale Coralloid Nano-Cu₃Sn Paste for High-Power Electronics Packaging. ACS Applied Electronic Materials, 2022, 4, 3457-3469.	4.3	5
8	Preparation and sintering properties of Cu10Sn3 IMCs nanopaste as die attach material for high temperature power electronics. Materials Letters, 2021, 282, 128845.	2.6	3
9	Advances in the modification and device integration of multiferroic bismuth ferrite. Ferroelectrics, 2021, 573, 87-102.	0.6	2
10	Dissimilatory iron reduction and potential methane production in Chagan Lake wetland soils with carbon addition. Wetlands Ecology and Management, 2021, 29, 369-379.	1.5	8
11	Facile synthesis of Cu10Sn3 nanoparticles and their sintering behavior for power device packaging. Results in Materials, 2021, 10, 100187.	1.8	0
12	Heterogeneous LiNbO3/Si Direct Bonding for Wavelength-Dependent Mid-Infrared Imaging. , 2021, , .		0
13	Maximum shear stress-controlled uniaxial tensile deformation and fracture mechanisms and constitutive relations of Snâ€"Pb eutectic alloy at cryogenic temperatures. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2021, 819, 141523.	5.6	19
14	Low-Temperature Co-hydroxylated Cu/SiO₂ Hybrid Bonding Strategy for a Memory-Centric Chip Architecture. ACS Applied Materials & Interfaces, 2021, 13, 38866-38876.	8.0	21
15	Preparation and characterization of self-assembled ZnO nanowire devices: nanowire strain sensor and homogeneous pâ€"n junction. Nanotechnology, 2021, 32, 495604.	2.6	0
16	Low-temperature Cu/SiO₂ hybrid bonding using a novel two-step cooperative surface activation. , 2021, , .		6
17	Ductile-to-brittle transition in fracture behaviors of common solder alloys over a temperature range down to -150 ÂºC. Materials Today Communications, 2021, 29, 102962.	1.9	3
18	Exposure to melamine cyanuric acid in adult mice induced thyroid dysfunction and circadian rhythm disorder. Ecotoxicology and Environmental Safety, 2021, 228, 112992.	6.0	4

#	Article	IF	Citations
19	High-efficiency extraction synthesis for high-purity copper nanowires and their applications in flexible transparent electrodes. Nano Materials Science, 2020, 2, 164-171.	8.8	27
20	Ohmic contact formation mechanisms of TiN film on 4Hâ€“SiC. Ceramics International, 2020, 46, 7142-7148.	4.8	3
21	Laser induced forward transfer of brittle Cu3Sn thin film. Journal of Manufacturing Processes, 2020, 60, 48-53.	5.9	3
22	Low-temperature bonding and interfacial failure behavior of Si/glass and glass/glass chips. , 2020, , .		0
23	Spontaneous formation of sub-4 nm nanocrystalline alloy via polymorphic phase transformation. Materials Research Letters, 2020, 8, 431-437.	8.7	2
24	Nanometer-Scale Heterogeneous Interfacial Sapphire Wafer Bonding for Enabling Plasmonic-Enhanced Nanofluidic Mid-Infrared Spectroscopy. ACS Nano, 2020, 14, 12159-12172.	14.6	54
25	Rapid pressureless and low-temperature bonding of large-area power chips by sintering two-step activated Ag paste. Journal of Materials Science: Materials in Electronics, 2020, 31, 6497-6505.	2.2	12
26	Recycled low-temperature direct bonding of Si/glass and glass/glass chips for detachable micro/nanofluidic devices. Journal of Materials Science and Technology, 2020, 46, 156-167.	10.7	21
27	Fabrication and characterization of silk fibroin coating on APTES pretreated Mg-Zn-Ca alloy. Materials Science and Engineering C, 2020, 110, 110742.	7.3	23
28	Electrodeposition fabrication of Cu@Ni core shell nanowire network for highly stable transparent conductive films. Chemical Engineering Journal, 2020, 390, 124495.	12.7	38
29	Unique buoyancy-force-based kinetics determination of beta to alpha phase transformation in bulk tin plates. Materials and Design, 2020, 190, 108550.	7.0	6
30	Microstructure characterization of Al2O3â€“Mulliteâ€“AlN multiphase ceramic film on Cr/WCu substrate. Journal of Materials Science: Materials in Electronics, 2020, 31, 5941-5947.	2.2	1
31	Progress in wafer bonding technology towards MEMS, high-power electronics, optoelectronics, and optofluidics. International Journal of Optomechatronics, 2020, 14, 94-118.	6.6	24
32	Investigation of Plasma Activation Directions for Low-Damage Direct Bonding. ECS Journal of Solid State Science and Technology, 2020, 9, 081004.	1.8	0
33	Low-temperature direct and indirect bonding using plasma activation for 3D integration. , 2020, , .		2
34	VUV/O3 activated direct heterogeneous bonding towards high-performance LiNbO3-based optical devices. Applied Surface Science, 2019, 495, 143576.	6.1	8
35	Pressureless low-temperature sintering of plasma activated Ag nanoparticles for high-power device packaging. Materials Letters, 2019, 256, 126620.	2.6	5
36	Direct Heterogeneous Bonding of SiC to Si, SiO2, and Glass for High-Performance Power Electronics and Bio-MEMS. , 2019, , .		2

#	Article	IF	Citations
37	MoirÃ©-Based Alignment Using Centrosymmetric Grating Marks for High-Precision Wafer Bonding. Micromachines, 2019, 10, 339.	2.9	6
38	Low-temperature direct bonding of Si and quartz glass using the APTES modification. Ceramics International, 2019, 45, 16670-16675.	4.8	12
39	Silk fibroin film-coated MgZnCa alloy with enhanced in vitro and in vivo performance prepared using surface activation. Acta Biomaterialia, 2019, 91, 99-111.	8.3	48
40	Laser sintering mechanism and shear performance of Cuâ€"Agâ€"Cu joints with mixed bimodal size Ag nanoparticles. Journal of Materials Science: Materials in Electronics, 2019, 30, 7787-7793.	2.2	5
41	One-Step Fabrication of Copper Nanopillar Array-Filled AAO Films by Pulse Electrodeposition for Anisotropic Thermal Conductive Interconnectors. ACS Omega, 2019, 4, 6092-6096.	3.5	11
42	Chemical and thermal robust tri-layer rGO/Ag NWs/GO composite film for wearable heaters. Composites Science and Technology, 2019, 174, 76-83.	7.8	29
43	Fabrication of SiC-on-insulator substrate via a low-temperature plasma activated bonding process. , 2019, , .		0
44	Pressureless Low-Temperature Sintering of Silver Nano-Solder Paste Based on Surface Activation. , 2019, , .		0
45	Fabrication of SiC/Si, SiC/SiO2, and SiC/glass heterostructures via VUV/O3 activated direct bonding at low temperature. Ceramics International, 2019, 45, 4094-4098.	4.8	26
46	A facile method for direct bonding of single-crystalline SiC to Si, SiO2, and glass using VUV irradiation. Applied Surface Science, 2019, 471, 196-204.	6.1	20
47	A novel cobalt-free CO2-stable perovskite-type oxygen permeable membrane. Journal of Membrane Science, 2019, 573, 504-510.	8.2	22
48	Low-temperature-solderable intermetallic nanoparticles for 3D printable flexible electronics. Acta Materialia, 2019, 162, 163-175.	7.9	29
49	Effect of electric current on grain orientation and mechanical properties of Cu-Sn intermetallic compounds joints. Journal of Alloys and Compounds, 2018, 753, 203-211.	5.5	35
50	Direct Homo/Heterogeneous Bonding of Silicon and Glass Using Vacuum Ultraviolet Irradiation in Air. Journal of the Electrochemical Society, 2018, 165, H3093-H3098.	2.9	19
51	Growth kinetics of Cu6Sn5 intermetallic compound in Cu-liquid Sn interfacial reaction enhanced by electric current. Scientific Reports, 2018, 8, 1775.	3.3	25
52	Solderless bonding with nanoporous copper as interlayer for high-temperature applications. Microelectronics Reliability, 2018, 80, 198-204.	1.7	10
53	Room-Temperature Direct Heterogeneous Bonding of Glass and Polystyrene Substrates. Journal of the Electrochemical Society, 2018, 165, B3091-B3097.	2.9	8
54	Communicationâ€"A Self-Contained Temperature Sensing Approach for Ultrafast Microwelding. Journal of the Electrochemical Society, 2018, 165, B220-B222.	2.9	4

#	Article	IF	Citations
55	Cohesively enhanced electrical conductivity and thermal stability of silver nanowire networks by nickel ion bridge joining. Scientific Reports, 2018, 8, 5260.	3.3	27
56	Robust tuning of Kirkendall void density in circuit interconnections through substrate strain annealing. Journal of Materials Science: Materials in Electronics, 2018, 29, 8287-8292.	2.2	1
57	Mechanisms for low-temperature direct bonding of Si/Si and quartz/quartz <i>via</i> VUV/O₃ activation. RSC Advances, 2018, 8, 11528-11535.	3.6	52
58	Low-temperature wafer direct bonding of silicon and quartz glass by a two-step wet chemical surface cleaning. Japanese Journal of Applied Physics, 2018, 57, 02BD02.	1.5	14
59	VUV/O<inf>3</inf> activated bonder for low-temperature direct bonding of Si-based materials. , 2018, , .		1
60	A Modified Interposer Fabrication Process by Copper Nano-Pillars Filled in Anodic Aluminum Oxide Film for 3D Electronic Package. Applied Sciences (Switzerland), 2018, 8, 2188.	2.5	5
61	Communicationâ€"Defect-Free Direct Bonding for High-Performance Glass-On-LiNbO3 Devices. Journal of the Electrochemical Society, 2018, 165, B727-B729.	2.9	8
62	The Fabrication of Micro-Array Channels with the Ultrafine-Grained LZ91 Mg-Li Alloy by Micro-Embossing. Micromachines, 2018, 9, 55.	2.9	12
63	Room-Temperature Bonding and Debonding of Glass and Polystyrene Substrates Based on VUV/O<inf>3</inf> Activated Bonding Method. , 2018, , .		0
64	Recent Progress in Rapid Sintering of Nanosilver for Electronics Applications. Micromachines, 2018, 9, 346.	2.9	33
65	Direct bonding of silicon and quartz glass using VUV/O3 activation and a multistep low-temperature annealing process. Applied Surface Science, 2018, 453, 416-422.	6.1	33
66	Solid-State Spalling of Ag3Sn in an Eutectic SnPb Solder Joint with an Ag Thin Film/Ge Cell. Journal of Electronic Materials, 2018, 47, 5625-5631.	2.2	3
67	Glass-on-LiNbO3 heterostructure formed via a two-step plasma activated low-temperature direct bonding method. Applied Surface Science, 2018, 459, 621-629.	6.1	42
68	Communicationâ€"Ag NW Networks Enhanced by Ni Electroplating for Flexible Transparent Electrodes. Journal of the Electrochemical Society, 2018, 165, D328-D330.	2.9	10
69	One-Step Fabrication of 3D Nanohierarchical Nickel Nanomace Array To Sinter with Silver NPs and the Interfacial Analysis. ACS Applied Materials & Interfaces, 2017, 9, 4798-4807.	8.0	17
70	Crystallized Bi 0.9 La 0.1 Fe 0.95 Mn 0.05 O 3 /Ba 0.7 Sr 0.3 Ti 0.95 Co 0.05 O 3 bilayer thin films with enhanced multiferroic properties. Applied Surface Science, 2017, 404, 162-167.	6.1	4
71	Laser-induced actuation of individual microsize liquid metal droplets on an open solid surface. Applied Physics Express, 2017, 10, 017202.	2.4	2
72	Fusion behaviour and mechanism of ultrafine Ag-Cu nanoparticles induced by electron beam irradiation. Journal of Materials Science: Materials in Electronics, 2017, 28, 8206-8210.	2.2	2

#	Article	IF	Citations
73	A Comparative Study: Void Formation in Silicon Wafer Direct Bonding by Oxygen Plasma Activation with and without Fluorine. ECS Journal of Solid State Science and Technology, 2017, 6, P7-P13.	1.8	25
74	Room-temperature direct bonding of silicon and quartz glass wafers. Applied Physics Letters, 2017, 110, .	3.3	29
75	Laser Sintering of Nano-Ag Particle Paste for High-Temperature Electronics Assembly. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 1050-1057.	2.5	7
76	Investigation of Thermal Treatment Processes for Dissimilar Wafer Bonding. ECS Transactions, 2017, 77, 143-152.	0.5	1
77	Microstructure evolution and thermostability of bondline based on Cu@Sn core-shell structured microparticles under high-temperature conditions. Materials and Design, 2017, 131, 196-203.	7.0	33
78	Study of electroless Sn-coated Cu microparticles and their application as a high temperature thermal interface material. Surface and Coatings Technology, 2017, 319, 230-240.	4.8	16
79	Enhanced shear strength of Cuâ€“Sn intermetallic interconnects with interlocking dendrites under fluxless electric current-assisted bonding process. Journal of Materials Science, 2017, 52, 1943-1954.	3.7	30
80	Low temperature nanojoining of silverâ€“copper nanopaste as die attach material for high temperature packaging. Journal of Materials Science: Materials in Electronics, 2017, 28, 5446-5451.	2.2	8
81	Mechanical properties and fracture mechanisms of Sn-3.0Ag-0.5Cu solder alloys and joints at cryogenic temperatures. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2017, 684, 697-705.	5.6	42
82	Micro heat pipe device utilizing extended nanofluidics. RSC Advances, 2017, 7, 50591-50597.	3.6	10
83	Low-temperature direct bonding of silicon to quartz glass wafer via sequential wet chemical surface activation. , 2017, , .		0
84	Mechanisms for Room-Temperature Fluorine Containing Plasma Activated Bonding. ECS Journal of Solid State Science and Technology, 2017, 6, P373-P378.	1.8	17
85	Ultrafast formation of unidirectional and reliable Cu3Sn-based intermetallic joints assisted by electric current. Intermetallics, 2017, 80, 26-32.	3.9	34
86	Investigation of moisture diffusion in plastic electronic packages by molecular dynamics simulation. , 2017, , .		2
87	Void propensity in solder joints on a single copper pad with a grain size spectrum tuned by strain annealing. , 2017, , .		0
88	Effect of multilayer films and current on IMC formation in solder joints. , 2017, , .		0
89	The Fabrication of the Cu/Ni/Cu surface multilayer nano-array and the interconnection with the SAC305 solder. , 2017, , .		0
90	Study on preparation and rapid laser sintering process of nano silver pastes. , 2017, , .		5

#	Article	IF	Citations
91	Interposer connection reliability using double-side solder bump for board-level vertical interconnection. , 2017, , .		1
92	The effect of voids at the Cu₃Sn/Cu interface on the failure behavior of the Cu/Sn63Pb37 solder joints under high-speed shear loading. , 2017, , .		0
93	Study on the pre-tinned effect in the electroless tin plating process. , 2017, , .		1
94	Rapid sintering of copper nanopaste by pulse current for power electronics packaging. , 2017, , .		5
95	Reliability prediction of different size solder bumps in thermal shock test using FEM. , 2017, , .		0
96	Investigation of bonding front propagation for wafer direct bonding. , 2017, , .		1
97	The mechanism study of low-temperature brittle fracture of bulk Sn-based solder. , 2017, , .		4
98	Copper-tin reaction and preparation of microsolder joints under high frequency alternating magnetic field. , 2017, , .		0
99	A novel method for bonding strength evaluation. , 2017, , .		0
100	Quasi in situ study about growth kinetics of Ag<inf>3</inf>Sn at the interface of eutectic SnPb/electroplated Ag soder joint in the long-term satellite. , 2017, , .		0
101	Fuzzy Comprehensive Evaluation Model for Flight Safety Evaluation Research Based on an Empowerment Combination. Advances in Intelligent Systems and Computing, 2017, , 1479-1491.	0.6	3
102	A novel surface humidity controlled bonder for low-temperature wafer bonding. , 2016, , .		1
103	Interconnection of Cu wire/Au plating pads using parallel gap resistance microwelding process. , 2016, , .		3
104	Degradation behaviors of micro ball grid array (Î¼BGA) solder joints under the coupled effects of electromigration and thermal stress. Journal of Materials Science: Materials in Electronics, 2016, 27, 11583-11592.	2.2	17
105	Synthesis and characterization of ultra-fine bimetallic Ag-Cu nanoparticles as die attach materials. , 2016, , .		1
106	Single crystal copper nanocrystallization and sintered with silver nanoparticles. , 2016, , .		0
107	Influence of low temperature on tensile properties and fracture behavior of Sn3Ag0.5Cu solder alloy. , 2016, , .		1
108	Low-temperature bonding process for the fabrication of hybrid glassâ€“membrane organ-on-a-chip devices. Journal of Micro/ Nanolithography, MEMS, and MOEMS, 2016, 15, 044502.	0.9	5

#	Article	IF	Citations
109	Sintering mechanism of the Cuâ€"Ag coreâ€"shell nanoparticle paste at low temperature in ambient air. RSC Advances, 2016, 6, 91783-91790.	3.6	56
110	Microstructure of solar cell interconnections by resistance welding. , 2016, , .		0
111	Preparation and Sintering Properties of Ag27Cu2Sn Nanopaste as Die Attach Material. Journal of Electronic Materials, 2016, 45, 5436-5442.	2.2	6
112	Extremely fast formation of Cu Sn intermetallic compounds in Cu/Sn/Cu system via a micro-resistance spot welding process. Journal of Alloys and Compounds, 2016, 687, 667-673.	5.5	50
113	The role of chloride ions in rapid synthesis of ultra-long silver nanowires for flexible electrodes. Materials Research Express, 2016, 3, 075007.	1.6	15
114	Study of interconnection between Ni nano-array and nano-Ag solder. , 2016, , .		1
115	Communicationâ€"Fluorinated Plasma Treatments Using PTFE Substrates for Room-Temperature Silicon Wafer Direct Bonding. ECS Journal of Solid State Science and Technology, 2016, 5, P393-P395.	1.8	6
116	Effects of temperature and dispersants on the phases and morphology of Agâ€"Cu nanoparticles. Journal of Materials Science: Materials in Electronics, 2016, 27, 10065-10069.	2.2	8
117	Facile synthesis of Cuâ€"Ag hybrid nanowires with strong surface-enhanced Raman scattering sensitivity. CrystEngComm, 2016, 18, 1200-1206.	2.6	17
118	Recent Progress in Ohmic Contacts to Silicon Carbide for High-Temperature Applications. Journal of Electronic Materials, 2016, 45, 267-284.	2.2	56
119	Optimization and modeling for one-step synthesis process of Agâ€"Cu nano-particles using DOE methodology. Journal of Materials Science: Materials in Electronics, 2016, 27, 4265-4274.	2.2	10
120	The influence of strengthening and recrystallization to the cracking behavior of Ni, Sb, Bi alloyed SnAgCu solder during thermal cycling. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2016, 652, 264-270.	5.6	30
121	TEM observation of interfacial compounds of SnAgCu/ENIG solder bump after laser soldering and subsequent hot air reflows. Materials Letters, 2016, 163, 254-257.	2.6	22
122	The influence of high melting point elements on the reliability of solder during thermal shocks. , 2015, , .		1
123	Effect of CeO2 particles on the high phosphorus electroless Ni layer. , 2015, , .		0
124	Degradation mechanisms of solder joints on printed circuit boards during storage determined by infrared multi-point temperature measurements. , 2015, , .		0
125	Joining of Silver Nanowires by Femtosecond Laser Irradiation Method. Materials Transactions, 2015, 56, 981-983.	1.2	9
126	Study on microstructure, texture and thermal properties of LPSO reinforced Mg-Zn-Y(-Gd) alloys. , 2015, , .		1

#	Article	IF	Citations
127	Low Temperature Sintering Cu₆Sn₅ Nanoparticles for Superplastic and Superâ€uniform High Temperature Circuit Interconnections. Small, 2015, 11, 4097-4103.	10.0	48
128	The Investigation of Quality of Life in 87 Chinese Patients with Disorders of Sex Development. BioMed Research International, 2015, 2015, 1-6.	1.9	12
129	In situ quantitative study of microstructural evolution at the interface of Sn3.0Ag0.5Cu/Cu solder joint during solid state aging. Journal of Alloys and Compounds, 2015, 634, 94-98.	5.5	19
130	Characterization of the Microstructure of an AlN-Mullite-Al2O3 Ceramic Layer on WCu Composite Alloy for Microelectronic Application. Journal of Electronic Materials, 2015, 44, 4154-4160.	2.2	5
131	Suppression of void nucleation in Sn3.0Ag0.5Cu/CU solder joint by rapid thermal processing. Materials Letters, 2015, 158, 252-254.	2.6	4
132	Effect of CeO₂ particles on the low phosphorus electroless Ni layer. , 2015, , .		0
133	Effect of Au-Sn IMCsâ€™ formation and morphologies on shear properties of laser reflowed micro-solder joints. Soldering and Surface Mount Technology, 2015, 27, 45-51.	1.5	20
134	Effect of Cu grain size on the voiding propensity at the interface of SnAgCu/Cu solder joints. Materials Letters, 2015, 144, 97-99.	2.6	33
135	Fabrication of Al₂O₃â€“Mulliteâ€“AlN Multiphase Ceramic Layer on Wâ€“Cu Substrates for Power Semiconductor Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 182-187.	2.5	8
136	Microstructures, corrosion and mechanical properties of as-cast Mgâ€“Znâ€“Yâ€“(Gd) alloys. Transactions of Nonferrous Metals Society of China, 2015, 25, 2172-2180.	4.2	51
137	Synthesis of CrO single crystal slices by firing under water vapor atmosphere. Materials Letters, 2015, 152, 13-16.	2.6	3
138	Electromigration-induced intermetallic growth and voids formation in symmetrical Cu/Sn/Cu and Cu/Intermetallic compounds (IMCs)/Cu joints. Journal of Materials Science: Materials in Electronics, 2015, 26, 2674-2681.	2.2	27
139	Effect of the Silver Content of SnAgCu Solder on the Interfacial Reaction and on the Reliability of Angle Joints Fabricated by Laser-Jet Soldering. Journal of Electronic Materials, 2015, 44, 733-743.	2.2	11
140	Joining of silver nanoparticles by femtosecond laser irradiation method. , 2015, , .		0
141	Rapid formation of full Cu-In intermetallic compounds (IMCs) joints under electric current. , 2015, , .		2
142	Study of surface metallization on 3D flexible stack package. , 2015, , .		0
143	Microstructures and Properties of As-Cast Mg92Zn4Y4 and Mg92Zn4Y3Gd1 Alloys with LPSO Phase. Rare Metal Materials and Engineering, 2015, 44, 1617-1622.	0.8	8
144	Research on Energy-saving Evaluation Index System for Heating Network. , 2015, , .		0

#	Article	IF	Citations
145	Economic analysis on application of exhaust air heat recovery in existing public buildings in the severe cold regions. , 2015, , .		1
146	Research and analysis of central heating systems in Changchun. , 2015, , 161-165.		0
147	Design and simulation research of Ground Source Heat Pump system in severe cold regions. , 2015, , 157-160.		0
148	Parallel gap resistance thick wire bonding for vertical interconnection in 3D assembly. , 2014, , .		0
149	A novel method to fabricate AlN-Al<inf>2</inf>O<inf>3</inf> multiphase ceramic layer on WCu alloy. , 2014, , .		0
150	Parallel-gap resistance welding between gold-plated silver interconnects and silver electrodes in germanium solar cells. , 2014, , .		8
151	Effect of modulation structure on the laser-ignited self-propagating behavior of Ti/Al multilayer films. , 2014, , .		0
152	Formation of single phase Cu-Sn IMCs via layer-by-layer electroplating of Cu and Sn metals. , 2014, , .		0
153	Rapid formation of Cu-Sn intermetallic compounds by strong electric current. , 2014, , .		1
154	Secondary optical design of LED lamps with high CRI and adjustable CCT. , 2014, , .		3
155	Relationship between morphologies and orientations of Cu6Sn5 grains in Sn3.0Ag0.5Cu solder joints on different Cu pads. Materials Characterization, 2014, 88, 58-68.	4.4	63
156	Cu nanoparticles of low polydispersity synthesized by a double-template method and their stability. Colloid and Polymer Science, 2014, 292, 715-722.	2.1	18
157	Effects of ultrasonic irradiation and cooling rate on the solidification microstructure of Snâ€“3.0Agâ€“0.5Cu alloy. Journal of Materials Processing Technology, 2014, 214, 13-20.	6.3	21
158	Phase transformation and fracture behavior of Cu/In/Cu joints formed by solidâ€“liquid interdiffusion bonding. Journal of Materials Science: Materials in Electronics, 2014, 25, 4170-4178.	2.2	21
159	Effects of Ba0.7Sr0.3TiO3-based buffer layers and La/Mn doping on the crystallization behavior and multiferroic properties of BiFeO3thin films. RSC Advances, 2014, 4, 55889-55896.	3.6	5
160	Ultrafine-Grain and Isotropic Cu/SAC305/Cu Solder Interconnects Fabricated by High-Intensity Ultrasound-Assisted Solidification. Journal of Electronic Materials, 2014, 43, 2467-2478.	2.2	21
161	Ultrarapid formation of homogeneous Cu6Sn5 and Cu3Sn intermetallic compound joints at room temperature using ultrasonic waves. Ultrasonics Sonochemistry, 2014, 21, 924-929.	8.2	51
162	Parallel gap resistance thick wire bonding for vertical interconnection in 3D assembly. , 2014, , .		0

#	Article	IF	Citations
163	A novel method to fabricate AlN-Al<inf>2</inf>O<inf>3</inf> multiphase ceramic layer on WCu alloy. , 2014, , .		0
164	Rapid formation of Cu-Sn intermetallic compounds by strong electric current. , 2014, , .		0
165	Formation of single phase Cu-Sn IMCs via layer-by-layer electroplating of Cu and Sn metals. , 2014, , .		0
166	Parallel-gap resistance welding between gold-plated silver interconnects and silver electrodes in germanium solar cells. , 2014, , .		0
167	Secondary optical design of LED lamps with high CRI and adjustable CCT. , 2014, , .		0
168	Fabrication of Cu6Sn5 single-crystal layer for under-bump metallization in flip-chip packaging. Intermetallics, 2013, 42, 52-55.	3.9	11
169	Shear Deformation Behaviors of Sn3.5Ag Lead-free Solder Samples. Journal of Materials Science and Technology, 2013, 29, 471-479.	10.7	9
170	Formation mechanism and orientation of Cu3Sn grains in Cuâ€“Sn intermetallic compound joints. Materials Letters, 2013, 110, 137-140.	2.6	74
171	Synthesis of multiferroic Bi0.9La0.1Fe0.95Mn0.05O3â€“Ba0.7Sr0.3TiO3â€“Ni0.8Zn0.2Fe2O4 nanotubes with one closed end using a template-assisted solâ€“gel process. CrystEngComm, 2013, 15, 2147.	2.6	12
172	Formation of AuSnx IMCs in Sn3.5Ag0.75Cu micro-solder joints fabricated by laser and hot air reflow processes. Journal of Materials Science: Materials in Electronics, 2013, 24, 217-223.	2.2	6
173	Rapid pressureless low-temperature sintering of Ag nanoparticles for high-power density electronic packaging. Scripta Materialia, 2013, 69, 789-792.	5.2	146
174	Electrochemical synthesis of Niâ€“S/CeO2 composite electrodes for hydrogen evolution reaction. Journal of Power Sources, 2013, 230, 10-14.	7.8	41
175	Multiferroic properties of La and Mn co-doped BiFeO3 nanofibers by solâ€“gel and electrospinning technique. Materials Letters, 2013, 90, 45-48.	2.6	70
176	Fabrication of multiferroic Ba0.7Sr0.3TiO3â€“Ni0.8Zn0.2Fe2O4 composite nanofibers by electrospinning. Materials Letters, 2013, 91, 55-58.	2.6	14
177	Rapid formation of Cu/Cu3Sn/Cu joints using ultrasonic bonding process at ambient temperature. Applied Physics Letters, 2013, 102, .	3.3	68
178	Surface-Tension-Driven Self-Assembly of 3-D Microcomponents by Using Laser Reflow Soldering and Wire Limiting Mechanisms. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 168-176.	2.5	5
179	Laser-induced self-propagating reaction in Ti/a-Si multilayer films. , 2013, , .		0
180	Effect of high temperature thermal aging on microstructural evolution of Sn3Ag0.5Cu/Cu solder joints. , 2013, , .		0

#	Article	IF	Citations
181	Molecular Dynamics study of thermal conductivity in bismuth telluride thin films. , 2013, , .		1
182	The effects of humidity and temperature aging test on flexible packaging LED module. , 2013, , .		7
183	RESEARCH ON MICROSTRUCTURE OF Pb-FREE BGASOLDER JOINT ASSEMBLED WITH Sn-Pb SOLDERDURING ISOTHERMAL AGING. Jinshu Xuebao/Acta Metallurgica Sinica, 2013, 49, 831.	0.3	2
184	Precision Study for Surface Tension Driven Self-assembly of Hingeless Structures. Journal of Applied Sciences, 2013, 13, 2807-2812.	0.3	0
185	Prediction of Municipal Solid Waste Production in Changchun City Based on Gray Model GM(1,5). Applied Mechanics and Materials, 2012, 178-181, 799-803.	0.2	2
186	Relationship between crack propagation trends and grains in SnAgCu interconnects. , 2012, , .		1
187	Development of a new die-attach process and related bonding tool for multi-chip LED module. , 2012, , .		0
188	Synthesis of multiferroic Ba<inf>0.7</inf>Sr<inf>0.3</inf>TiO<inf>3</inf>-based thin films for memory devices by chemical solution deposition. , 2012, , .		0
189	Effect of grain orientation on electromigration degradation in lead-free solder joints. , 2012, , .		1
190	The Process Optimization of EFO for Copper Wire Bonding. Advanced Materials Research, 2012, 482-484, 763-766.	0.3	0
191	Oxidation and Auâ€Sn reaction of laser reflowed microâ€solder joints protected by N2 or exposed to air atmosphere. Soldering and Surface Mount Technology, 2012, 24, 191-196.	1.5	10
192	Ultrasonic Bondability and Antioxidation Property of Ti/Cu/TaN/Ag Multi-layers on Si Substrate. Thin Solid Films, 2012, 524, 224-228.	1.8	4
193	Theoretical study on power factor of Si/Ge multi-layer thermoelectric micro-cooler. , 2012, , .		0
194	Ultrasonic-induced deformation nanostructures in coarse-grained aluminum wires at room temperature. , 2012, , .		0
195	The effect of voids on thermal conductivity of solder joints. , 2012, , .		6
196	Mechanism of low temperature Cu-In Solid-Liquid Interdiffusion bonding in 3D package. , 2012, , .		8
197	Growth and shear strength of intermetallic compounds in Sn-Ag-Cu solder joints. , 2012, , .		0
198	Dynamic model for analyzing the motion of molten solder during self-assembly. , 2012, , .		2

#	Article	IF	Citations
199	Fabrication of interconnects using pressureless low temperature sintered Ag nanoparticles. Materials Letters, 2012, 85, 61-63.	2.6	70
200	Morphologies and grain orientations of Cuâ€“Sn intermetallic compounds in Sn3.0Ag0.5Cu/Cu solder joints. Materials Letters, 2012, 86, 157-160.	2.6	26
201	Interfacial reactions of eutectic Sn3.5Ag and pure tin solders with Cu substrates during liquid-state soldering. Intermetallics, 2012, 25, 86-94.	3.9	57
202	Thermal characterization of high power LED array in aluminum base copper clad laminate package. , 2012, , .		0
203	Effect of Diamond Additions on Wettability and Distribution of SnAgCu Composite Solder. Journal of Materials Science and Technology, 2012, 28, 661-665.	10.7	13
204	Niâ€“CeO2 composite cathode material for hydrogen evolution reaction in alkaline electrolyte. International Journal of Hydrogen Energy, 2012, 37, 13921-13932.	7.1	94
205	Synthesis of Co-doped barium strontium titanate nanofibers by solâ€“gel/electrospinning process. Materials Letters, 2012, 75, 207-210.	2.6	15
206	Investigation of fluorine containing plasma activation for room-temperature bonding of Si-based materials. Microelectronics Reliability, 2012, 52, 347-351.	1.7	23
207	Mechanical properties and microstructures of hybrid ultrasonic resistance brazing of WC-Co/BeCu. Journal of Materials Processing Technology, 2012, 212, 1885-1891.	6.3	17
208	Effect of intermetallic compounds on fracture behaviors of Sn3.0Ag0.5Cu lead-free solder joints during in situ tensile test. Journal of Materials Science: Materials in Electronics, 2012, 23, 136-147.	2.2	18
209	Development of a three-dimensional integrated solder ball bumping & bonding method for MEMS devices. , 2011, , .		2
210	Effect of quantum effects on electrical transport in Si/Ge/Si sandwich structure. , 2011, , .		0
211	Analysis of Cu6Sn5 grain orientations in Sn3.0Ag0.5Cu lead-free solder joints. , 2011, , .		2
212	Effects of bump size on deformation and fracture behavior of Sn3.0Ag0.5Cu/Cu solder joints during shear testing. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2011, 529, 468-478.	5.6	51
213	Reliability and failure analysis of fine copper wire bonds encapsulated with commercial epoxy molding compound. Microelectronics Reliability, 2011, 51, 157-165.	1.7	30
214	Self-assembly of three-dimensional microstructures in MEMS via fluxless laser reflow soldering. , 2011, , .		5
215	Room-Temperature Direct Bonding Using Fluorine Containing Plasma Activation. Journal of the Electrochemical Society, 2011, 158, H525.	2.9	26
216	Study of synthetic aperture ladar imaging through atmospheric turbulence. Proceedings of SPIE, 2011, , .	0.8	1

#	Article	IF	Citations
217	Multi-layer model vs. single-layer model for N and P doped poly layers in etch bias modeling. , 2010, , .		1
218	Investigation on Sn grain number and crystal orientation in the Snâ€"Agâ€"Cu/Cu solder joints of different sizes. Journal of Materials Science: Materials in Electronics, 2010, 21, 1174-1180.	2.2	28
219	Effect of protection atmosphere's temperature on morphology of Au-Sn IMCs in laser reflowed micro-solder joints. , 2010, , .		1
220	Advances in thermoelectric microcooling. , 2010, , .		0
221	Improved modeling for solder joint geometry and self-alignment in flip chip bonding. , 2010, , .		2
222	Ultrasonic bondability and antioxidation property of Ti/Cu/Ag metallization on Si substrate. , 2010, , .		1
223	Study of MEMS self-assembly using molten solder ball. , 2010, , .		1
224	Finite element analysis of electromigration reliability in copper chip interconnect. , 2010, , .		0
225	Experimental Study on Air-Source Heat Pump Using Exhaust of Building as Heating Source. , 2010, , .		0
226	MICROSTRUCTURE AND RELIABILITY OF LASER JET SOLDER BALL BONDING SOLDER JOINTS. Jinshu Xuebao/Acta Metallurgica Sinica, 2010, 46, 1115-1120.	0.3	3
227	ULTRASONIC BONDABILITY AND ANTIOXIDATION PROPERTY OF TiN/Ag METALLIZATION ON Cu PAD. Jinshu Xuebao/Acta Metallurgica Sinica, 2010, 46, 618-622.	0.3	0
228	Characterization of ag nanofilm metallization on copper chip interconnect and its ultrasonic bondability. , 2009, , .		1
229	Modeling of an oblique impact of solder droplet onto a groove with the impact point to be offset from the groove surfaces interface. Journal of Materials Science, 2009, 44, 1772-1779.	3.7	2
230	Effect of electronic flame off parameters on copper bonding wire: Free-air ball deformability, heat affected zone length, heat affected zone breaking force. Microelectronic Engineering, 2009, 86, 2094-2103.	2.4	34
231	In situ measurement of bond resistance varying with process parameters during ultrasonic wedge bonding. Journal of Materials Processing Technology, 2009, 209, 139-144.	6.3	7
232	Shape and fatigue life prediction of chip resistor solder joints. , 2009, , .		4
233	Modeling thermal fatigue in anisotropic Sn-Ag-Cu/Cu solder joints. , 2009, , .		4
234	Depiction of the elastic anisotropy of AuSn<inf>4</inf> and AuSn<inf>2</inf> from first-principles calculations. , 2009, , .		0

#	Article	IF	Citations
235	Effect of Cu addition in sn-containing solder joints on interfacial reactions with Au foils. , 2009, , .		0
236	Modeling of Micropitch Shift of a Magnetoelectrical Sensor During Laser Solder Ball Bonding Process. IEEE Transactions on Advanced Packaging, 2009, 32, 136-145.	1.6	4
237	Determination of the Elastic Properties of Cu3Sn Through First-Principles Calculations. Journal of Electronic Materials, 2008, 37, 477-482.	2.2	38
238	Determination of the Elastic Properties of Au5Sn and AuSn from Ab Initio Calculations. Journal of Electronic Materials, 2008, 37, 968-974.	2.2	16
239	Bonding wire characterization using automatic deformability measurement. Microelectronic Engineering, 2008, 85, 1795-1803.	2.4	25
240	Finite element modeling of electron beam welding of a large complex Al alloy structure by parallel computations. Journal of Materials Processing Technology, 2008, 199, 41-48.	6.3	38
241	Investigation of ultrasonic copper wire wedge bonding on Au/Ni plated Cu substrates at ambient temperature. Journal of Materials Processing Technology, 2008, 208, 179-186.	6.3	47
242	Microstructural study of copper free air balls in thermosonic wire bonding. Microelectronic Engineering, 2008, 85, 1815-1819.	2.4	36
243	Growth behavior of Cu/Al intermetallic compounds and cracks in copper ball bonds during isothermal aging. Microelectronics Reliability, 2008, 48, 416-424.	1.7	211
244	Nano features of Al/Au ultrasonic bond interface observed by high resolution transmission electron microscopy. Materials Characterization, 2008, 59, 1419-1424.	4.4	24
245	Investigation of sagging phenomenon observed in laser reflow soldering right-angled solder joints during isothermal aging or thermal cycle process. Journal of Alloys and Compounds, 2008, 458, 323-329.	5.5	3
246	Bonding mechanism of ultrasonic wedge bonding of copper wire on Au/Ni/Cu substrate. Transactions of Nonferrous Metals Society of China, 2008, 18, 132-137.	4.2	24
247	Effect of Zn addition in Sn-rich alloys on interfacial reaction with Au foils. Transactions of Nonferrous Metals Society of China, 2008, 18, 617-622.	4.2	4
248	Effect of solidification on solder bump formation in solder jet process: Simulation and experiment. Transactions of Nonferrous Metals Society of China, 2008, 18, 1201-1208.	4.2	20
249	Effect of laser input energy on AuSnx intermetallic compounds formation in solder joints with different thickness of Au surface finish on pads. Acta Metallurgica Sinica (English Letters), 2008, 21, 183-190.	2.9	1
250	Nanoscale analysis of ultrasonic wedge bond interface by using high-resolution transmission electron microscopy. , 2008, , .		0
251	Numerical simulation of solder spreading and solidification during solder jet bumping process. , 2008, , .		0
252	Effect of Thermal Aging on the Microstructure Evolution and Solder Joint Reliability in Hard Disk Drive Under Mechanical Shock. IEEE Transactions on Components and Packaging Technologies, 2008, 31, 831-836.	1.3	3

#	Article	IF	Citations
253	First-principles study on the elastic anisotropy of Au-Sn intermetallic compounds. , 2008, , .		0
254	Limited Î²-Sn grain number of miniaturized Sn-Ag-Cu solder joints. , 2008, , .		1
255	Shear fracture behavior of Sn3.0Ag0.5Cu solder joints on Cu pads with different solder volumes. , 2008, , .		3
256	Configuration Knowledge Expression Based on TLAC for ETO Product in Mass Customization. , 2008, , .		0
257	Resist bias measured in Iso-focal structure. , 2008, , .		1
258	Investigation of interfacial reaction between eutectic Snâ€"Pb solder droplet and Au/Ni/Cu pad. Materials Science and Technology, 2008, 24, 744-750.	1.6	2
259	Three-dimensional modelling of solder droplet impact onto a groove. Journal Physics D: Applied Physics, 2008, 41, 245503.	2.8	5
260	Research on Configuration Process of ATO Product for Mass Customization. , 2008, , .		0
261	Research on Knowledge Expression of ETO Product for Mass Customization. , 2008, , .		1
262	Numerical and Experimental Analysis of Solder Joint Self-Alignment in Fiber Attachment Soldering. Journal of Electronic Packaging, Transactions of the ASME, 2008, 130, .	1.8	1
263	Design of uniform solder droplets jet system. Jixie Gongcheng Xuebao/Chinese Journal of Mechanical Engineering, 2008, 44, 163.	0.5	0
264	The Impact of Defect formed in Hot-cutting Process on Reliability of Ceramic Packaging And A Novel Structure Design Concept. , 2007, , .		0
265	Effects of Cu Addition on Growth of Au-Sn Intermetallics at Sn-xCu/Au Interface during Aging Process. , 2007, , .		0
266	Influence of aging treatment on deformation behavior of 96.5Sn3.5Ag lead-free solder alloy during in situ tensile tests. Journal of Alloys and Compounds, 2007, 428, 274-285.	5.5	67
267	A Computational Model of a Molten Solder Droplet Spreading on Orthogonal Pads. , 2007, , .		0
268	Effects of Cu Addition on Growth of Au-Sn Intermetallics at Sn-xCu/Au Interface during Aging Process. , 2007, , .		0
269	Sagging Phenomenon of Micro-Solder Joints Fabricated by Laser Reflow Process. , 2007, , .		0
270	Design of Solder Joint for Self-Alignment in Optical Fiber Attachment Soldering. , 2007, , .		2

#	Article	IF	Citations
271	Observation of Ultrasonic Al-Si Wire Wedge Bond Interface Using High Resolution Transmission Electron Microscope. , 2007, , .		1
272	Comparison of interface evolution of ultrasonic aluminum and gold wire wedge bonds during thermal aging. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2007, 447, 111-118.	5.6	17
273	Evolution of the bond interface during ultrasonic Alâ€"Si wire wedge bonding process. Journal of Materials Processing Technology, 2007, 182, 202-206.	6.3	24
274	Evolution of Cu/Al Intermetallic Compounds in the Copper Bump bonds during Aging Process. , 2007, , .		8
275	Effects of Solder Volume on Formation and Redeposition of Au-Containing Intermetallics in Ni/Au-SnAgCu-Ni(P) Solder Joints. Journal of Electronic Materials, 2007, 36, 33-39.	2.2	8
276	Cross-Interaction of Interfacial Reactions in Ni (Au/Ni/Cu)-SnAg-Cu Solder Joints during Reflow Soldering and Thermal Aging. Journal of Electronic Materials, 2007, 36, 26-32.	2.2	17
277	Numerical and Experimental Study on Solder Joint Self-Alignment Behavior for Optical Fiber Attachment Assembly. , 2006, , .		0
278	Modeling of Three-Dimensional Geometry of Solder Joint in Fiber Attachment Soldering. , 2006, , .		1
279	Interfacial Characterization and Bonding Mechanism of Ultrasonic Wedge Bonding. , 2006, , .		5
280	The Research Status of Stress and Failure Analysis in Ceramic Packaging. , 2006, , .		0
281	Prediction of Micro Pitch Motion of a Microsensor Component during Laser Soldering Interconnection Process. , 2006, , .		0
282	The effects of pulsed Nd:YAG laser irradiation on surface energy of copper. Applied Surface Science, 2006, 252, 4257-4263.	6.1	16
283	In situ TEM observation of microcrack nucleation and propagation in pure tin solder. Materials Science and Engineering B: Solid-State Materials for Advanced Technology, 2006, 127, 62-69.	3.5	12
284	Interdiffusion of Alâ€"Ni system enhanced by ultrasonic vibration at ambient temperature. Ultrasonics, 2006, 45, 61-65.	3.9	26
285	In-situ observation on microfracture behavior ahead of the crack tip in 63Sn37Pb solder alloy. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2006, 37, 1017-1025.	2.2	4
286	The Microstructure of Eutectic Au-Sn and In-Sn Solders on Au/Ti and Au/Ni Metallizations during Laser Solder Bonding Process for Optical Fiber Alignment. , 2006, , .		0
287	Comparison of Bond Interface Reaction in Al-Ni and Al-Au Systems Formed by Ultrasonic Wedge Bonding. , 2006, , .		0
288	In-Situ observation on microfracture behavior ahead of the crack tip in 63Sn37Pb solder alloy. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2006, 37, 1017-1025.	2.2	0

#	Article	IF	Citations
289	In-Situ observation on microfracture behavior ahead of the crack tip in 63Sn37Pb solder alloy. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2006, 37, 1017-1025.	2.2	0
290	Nd:YAG laser surface treatment of copper to improve the wettability of Sn3.5Ag solder on copper. Surface and Coatings Technology, 2005, 200, 2181-2186.	4.8	6
291	Evolution of deformation near the triple point of grain junctions in Sn-based solders during in situ tensile test. Materials Letters, 2005, 59, 697-700.	2.6	11
292	Scanning electron microscope in-situ investigation of fracture behavior in 96.5Sn3.5Ag lead-free solder. Journal of Electronic Materials, 2005, 34, 1324-1335.	2.2	12
293	In-situ SEM observation on fracture behaviors of Sn-based solder alloys. Journal of Materials Science, 2005, 40, 1993-2001.	3.7	6
294	Thermomechanical behaviour of PBGA package during laser and hot air reflow soldering. Modelling and Simulation in Materials Science and Engineering, 2004, 12, 235-243.	2.0	16
295	Aging effects on fracture behavior of 63Sn37Pb eutectic solder during tensile tests under the SEM. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2004, 384, 314-323.	5.6	19
296	Aging effects on fracture behavior of 63Sn37Pb eutectic solder during tensile tests under the SEM. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2004, 384, 314-323.	5.6	50
297	Characteristics of interfacial microstructure of PBGA solder bump during multi-reflow and aging processes. , 2003, , .		2
298	Self-sensed inspection of joint temperature for thin-film sensors. , 2003, , .		0
299	Parallel gap bonding mechanism of joint formation for thin-film metallization. , 2003, , .		2
300	Design of laser scanning solder bumping system. , 2003, , .		1
301	Laser ink-jet solder bump fabrication for electronic interconnection. , 2003, , .		0
302	Interaction kinetics between PBGA solder balls and Au/Ni/Cu metallisation during laser reflow bumping. Soldering and Surface Mount Technology, 2003, 15, 17-21.	1.5	8
303	Electronic structure calculation for properties of Sn-based solder alloys with the relativistic DV-XÎ± method. Modelling and Simulation in Materials Science and Engineering, 2002, 10, 121-129.	2.0	4
304	Electronic structure mechanism for the wettability of Sn-based solder alloys. Journal of Electronic Materials, 2002, 31, 185-190.	2.2	40
305	Intermetallic compounds formation at interface between PBGA solder ball and Au/Ni/Cu/BT PCB substrate after laser reflow processes. Materials Science and Engineering B: Solid-State Materials for Advanced Technology, 2002, 95, 254-262.	3.5	35
306	<title>Investigation on bridge in QFP and fatigue in BGA based on simulating solder joint formation</title>. , 2000, , .		0

#	Article	IF	Citations
307	An integrated system for prediction and analysis of solder interconnection shapes. IEEE Transactions on Electronics Packaging Manufacturing, 2000, 23, 87-92.	1.4	21
308	<title>Automatic computer-aided system of simulating solder joint formation</title>. , 1999, , .		0
309	Computer simulation of three-dimensional castellated solder joint geometry in surface mount technology. Modelling and Simulation in Materials Science and Engineering, 1998, 6, 557-565.	2.0	8
310	Evolution of intermetallic compounds at interface between PBGA solder ball and pads during laser reflow soldering. , 0, , .		3
311	Thermalmechanical behavior of PBGA package during laser and hot air reflow soldering. , 0, , .		1
312	The effects of laser reflow conditions on the formation of intermetallic compounds at Sn3.0Ag0.5Cu solder/Cu joint interface. , 0, , .		1
313	Heat transfer analyses of molten droplet solder bumping for electronic interconnection. , 0, , .		0
314	Comparison of AuSnx IMCs’s Morphology, Distribution in Lead-free Solder Joints Fabricated by Laser and Hot Air Reflow Process. , 0, , .		3
315	IMC Evolution and Reliability of Lead-free Solder Bump Formed by Induction Self Heat Reflow. , 0, , .		1
316	Microstructure of Sn-Ag-Cu lead-free flip chip interconnects during aging. , 0, , .		0
317	Study of copper free air ball in thermosonic copper ball bonding. , 0, , .		14
318	Effect of thermal aging on microstructure, shear and mechanical shock failures for solder ball bonding joint. , 0, , .		1
319	Effect of laser input energy on wetting areas of solder and formation of intermetallic compounds at Sn-3.5Ag-0.75Cu/Au right-angled joint interface. , 0, , .		1
320	Interfacial Reaction between Lead-free Solder Ball and Au/Ni/Cu Pad during Laser Reflow Soldering. , 0, , .		3
321	Molecular dynamics (MD) simulation of uniaxial tension of β-Sn single crystals with nanocracks. , 0, , .		0
322	Development of fluxes for selected Sn-Cu based lead-free solders. , 0, , .		1
323	The diffusion of Ni into Al wire at the interface of ultrasonic wire bond during high temperature storage. , 0, , .		1
324	A new solder bumping technology with local induction heating. , 0, , .		0

#	Article	IF	Citations
325	Solar Water Heating System and Building Integration of High-Rise Building in Seismic Zone. Advanced Materials Research, 0, 512-515, 163-167.	0.3	0
326	Manufacturing and Microstructure of Cu Coated Diamonds/SnAgCu Composite Solder Bumps. Applied Mechanics and Materials, 0, 288, 323-327.	0.2	1
327	Hybrid Plasma Activation Strategy for the Proteinâ€Coated Magnesium Implants in Orthopedic Applications. Advanced Materials Interfaces, 0, , 2101724.	3.7	2